

IN THE SPECIFICATION

Paragraph starting at page 6, second line from the bottom:

As shown in Fig. 2, the insulating substrate 16 is divided into wiring regions 28, a chip region 30 enclosed by the wiring regions 28, and a reinforcement layer region 32 at the peripheral edge portion of the insulating substrate 16 so as to enclose the wiring regions 28. Fig. 2 shows that the semiconductor chip region 30 does not overlap the reinforcement layer region 32, the semiconductor chip region 30 does not overlap the wiring regions 28, and the wiring regions 28 are disposed between the semiconductor chip region 30 and the reinforcement layer region 32. The wirings 18 are formed in the wiring regions 28, and the reinforcement layers 20 are formed in the reinforcement layer region 32. The wirings 18 and the reinforcement layers 20 are formed by plating a metal material such as copper. It should be noted that the reinforcement layers 20 are not limited to a metal material such as copper and may be formed using a conductive material or an insulating material.